

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method for producing a wiring transfer sheet comprising a carrier base and a wiring layer formed on a surface of the carrier base, the method comprising:

~~superposing on a surface of the carrier base a sheet of a wiring material having a first rough surface so that the first rough surface contacts the surface of the carrier base;~~

~~forming on the surface of the carrier base a second rough surface complementary to the first rough surface of the sheet of the wiring material; and~~

pressing a sheet of wiring material having a first rough surface against a surface of the carrier base such that:

the first rough surface is in contact with the surface of the carrier base during said pressing;

the sheet of wiring material is separably positioned on the surface of the carrier base by said pressing; and

the surface of the carrier base is formed into a second rough surface complementary to the first rough surface of the sheet of wiring material due to pressure from the first rough surface against the surface of the carrier base; and

forming a wiring layer with a predetermined wiring pattern on the surface of the carrier base by etching the sheet of wiring material.

2. (Previously Presented) The method according to claim 1, wherein the first rough surface is a surface having a plurality of convexities.

Claims 3-6 (Cancelled).

7. (Previously Presented) A wiring transfer sheet produced according to the method of claim 1.

8. (New) The method according to claim 1, further comprising forming the first rough surface by depositing metal particles on a surface of the sheet of wiring material to form convexities.

9. (New) The method according to claim 8, wherein said depositing the metal particles is performed by electrolytic plating.

10. (New) The method according to claim 1, further comprising subjecting the surface of the carrier base to a releasing treatment before said pressing of the sheet of wiring material against the surface of the carrier base.

11. (New) The method according to claim 10, wherein said releasing treatment comprises coating a silicone resin on the surface of the carrier base.

12. (New) The method according to claim 11, wherein said coating of the silicone resin comprising coating the silicone resin on the surface of the carrier base to a thickness of between 0.01 μm and 1.0 μm .

13. (New) The method according to claim 10, further comprising forming the first rough surface by depositing metal particles on a surface of the sheet of wiring material to form convexities.

14. (New) The method according to claim 13, wherein said depositing the metal particles is performed by electrolytic plating.